



COPY OF PAPER  
ORIGINALLY FILED

Practitioner's Docket No. U 13887-9

RECEIVED  
PATENT  
SEP 17 2002

TECHNOLOGY CENTER 2800

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of: Sung-Fei WANG, et al.  
Serial No.: 10/087,432  
Filed: March 1, 2002

For: **STACKED SEMICONDUCTOR CHIP PACKAGE**

**Assistant Commissioner for Patents  
Washington, D.C. 20231**

Sir:

**PRELIMINARY AMENDMENT**

Please amend the above identified application as follows:

**IN THE CLAIMS :**

Please cancel claims 1-4:

Please add new claims 5-10

---

**CERTIFICATE OF MAILING (37 CFR 1.8a)**

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to the: Assistant Commissioner for Patents, Washington, D.C. 20231

Date: April 24, 2002

  
(Signature of person mailing paper)

William R. Evans  
(type or print name of person certifying)